

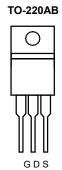
RU7088A-VB Datasheet N-Channel 60 V (D-S) MOSFET

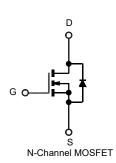
| PRODUCT SUMMARY | | | |
|---------------------------|--------|----|--|
| V _{DS} | 60 | V | |
| $R_{DS(on)}V_{GS} = 10 V$ | 5 | mΩ | |
| I _D | 120 | Α | |
| Configuration | Single | | |

FEATURES

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:







| ABSOLUTE MAXIMUM RATINGS (T _C = 25 | °C, unless other | vise noted) | | | |
|---|---------------------------|-----------------------------------|--------------------------------------|------|--|
| Parameter | | Symbol | Limit | Unit | |
| Gate-Source Voltage | | V _{GS} | ± 20 | V | |
| Continuous Drain Current (T _J = 175 °C) ^b | T _C = 25 °C | l _D | 120 | | |
| | T _C = 100 °C | | 90 | 1 | |
| Pulsed Drain Current | | I _{DM} | 350 | Α | |
| Continuous Source Current (Diode Conduction) | | I _S | 70ª | | |
| Avalanche Current | | I _{AS} 50 | | | |
| Single Avalanche Energy (Duty Cycle ≤ 1 %) | L = 0.1 mH | E _{AS} | 125 | mJ | |
| Maximum Power Dissipation | $T_C = 25 ^{\circ}C$ 136 | 136 | W | | |
| Maximum Fower Dissipation | T _A = 25 °C | טי | 3 ^b , 8.3 ^{b, c} | VV | |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | - 55 to 175 | °C | |

| THERMAL RESISTANCE RATINGS | | | | | |
|--|--------------|-------------------|---------|---------|------|
| Parameter | | Symbol | Typical | Maximum | Unit |
| Marrian una lun ation to Analismta | t ≤ 10 sec | R _{thJA} | 15 | 18 | |
| Maximum Junction-to-Ambient ^a | Steady State | thJA | 40 | 50 | °C/W |
| Maximum Junction-to-Case | | R _{thJC} | 0.85 | 1.1 | |

Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c. $t \le 10 \text{ s}$.



| Parameter | Symbol | Test Conditions | Min. | Typ.a | Max. | Unit | |
|---|---------------------|--|------|-------|-------|------|--|
| Static | | | ı | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | V _{GS} = 0 V, I _D = 250 μA | 60 | | | V | |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} = V _{GS} , I _D = 250 μA | | 2 | | V | |
| Gate-Body Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | | | ± 100 | nA | |
| | | V _{DS} = 60 V, V _{GS} = 0 V | | | 1 | μA | |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 60 V, V _{GS} = 0 V, T _J = 125 °C | | | 50 | | |
| | | V _{DS} = 60 V, V _{GS} = 0 V, T _J = 175 °C | | | 250 | 1 | |
| On-State Drain Current ^b | I _{D(on)} | V _{DS} = 5 V, V _{GS} = 10 V | 60 | | | Α | |
| | | V _{GS} = 10 V, I _D = 20 A | | 5 | | | |
| Drain-Source On-State Resistance ^b | | V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C | | 10 | | | |
| | R _{DS(on)} | V _{GS} = 10 V, I _D = 20 A, T _J = 175 °C | | 15 | | mΩ | |
| | | $V_{GS} = 7.5 \text{ V}, I_D = 15 \text{ A}$ | | 8 | | | |
| Forward Transconductance ^b | 9 _{fs} | V _{DS} = 15 V, I _D = 20 A | | 60 | | S | |
| Dynamic | | | | · | | | |
| Input Capacitance | C _{iss} | | | 6800 | | | |
| Output Capacitance | C _{oss} | $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$ | | 570 | | pF | |
| Reverse Transfer Capacitance | C _{rss} | | | 325 | | | |
| Total Gate Charge ^c | Qg | | | 47 | 70 | | |
| Gate-Source Charge ^c | Q _{gs} | $V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$ | | 10 | | nC | |
| Gate-Drain Charge ^c | Q _{gd} | | | 12 | | | |
| Turn-On Delay Time ^c | t _{d(on)} | | | 10 | 20 | | |
| Rise Time ^c | t _r | V_{DD} = 30 V, R_L = 0.6 Ω | | 15 | 25 | | |
| Turn-Off Delay Time ^c | t _{d(off)} | $I_D \cong 50$ A, V_{GEN} = 10 V, R_g = 2.5 Ω | | 35 | 50 | ns | |
| Fall Time ^c | t _f | | | 20 | 30 | | |
| Source-Drain Diode Ratings and Cha | aracteristics (| T _C = 25 °C) | | | | | |
| Pulsed Current | I _{SM} | 350 | | | Α | | |
| Diode Forward Voltage | V _{SD} | I _F = 20 A, V _{GS} = 0 V | | 1 | 1.5 | V | |
| Reverse Recovery Time | t _{rr} | I _F = 20 A, di/dt = 100 A/μs | | 45 | 100 | ns | |

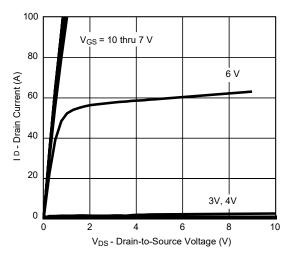
Notes:

- a. For design aid only; not subject to production testing. b. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- c. Independent of operating temperature.

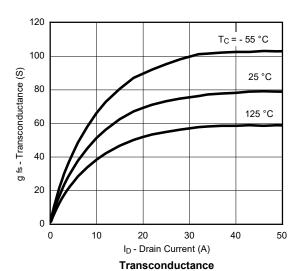
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



TYPICAL CHARACTERISTICS (25 °C unless noted)



Output Characteristics



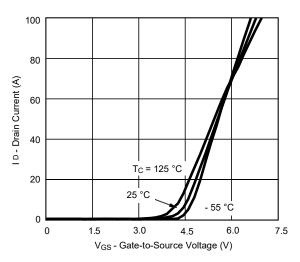
C - Capacitance (pF) 2000 2000 2000 2000 2000 2000 C_{oss} 1000 C_{rss} 0

20

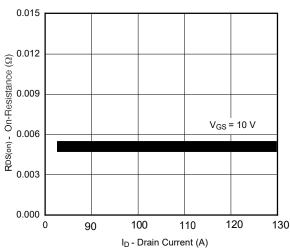
 C_{iss}

V_{DS} - Drain-to-Source Voltage (V) Capacitance

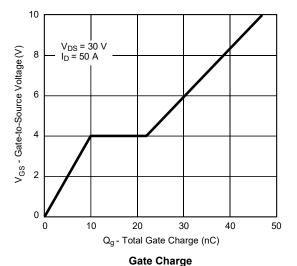
30



Transfer Characteristics



On-Resistance vs. Drain Current



0

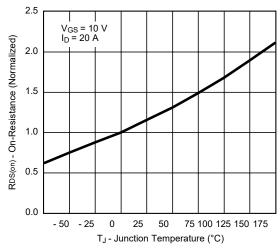
8000

7000

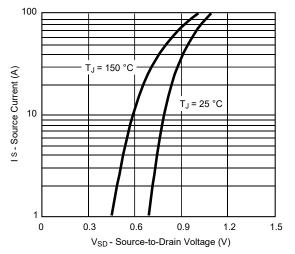
6000



TYPICAL CHARACTERISTICS (25 °C unless noted)



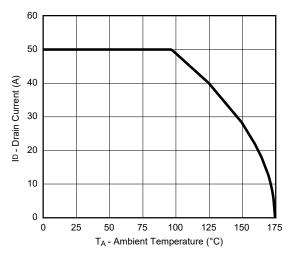
On-Resistance vs. Junction Temperature



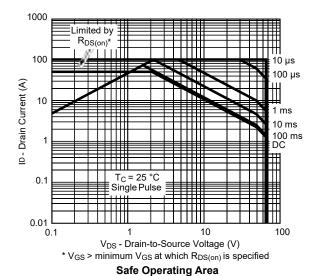
Source-Drain Diode Forward Voltage

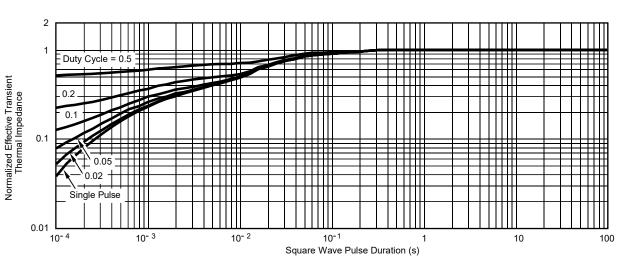


THERMAL RATINGS



Maximum Drain Current vs. Ambient Temperature





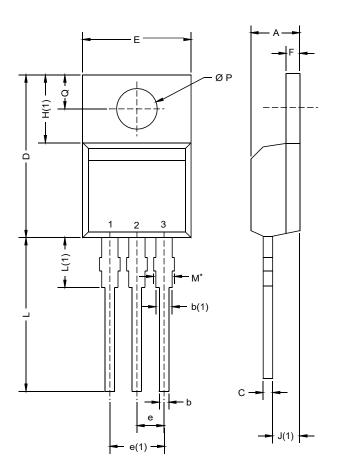
Normalized Thermal Transient Impedance, Junction-to-Case

服务热线:400-655-8788

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TO-220AB



| DIM. | MILLIMETERS | | INCHES | | |
|------|-------------|-------|--------|-------|--|
| | MIN. | MAX. | MIN. | MAX. | |
| Α | 4.25 | 4.65 | 0.167 | 0.183 | |
| b | 0.69 | 1.01 | 0.027 | 0.040 | |
| b(1) | 1.20 | 1.73 | 0.047 | 0.068 | |
| С | 0.36 | 0.61 | 0.014 | 0.024 | |
| D | 14.85 | 15.49 | 0.585 | 0.610 | |
| Е | 10.04 | 10.51 | 0.395 | 0.414 | |
| е | 2.41 | 2.67 | 0.095 | 0.105 | |
| e(1) | 4.88 | 5.28 | 0.192 | 0.208 | |
| F | 1.14 | 1.40 | 0.045 | 0.055 | |
| H(1) | 6.09 | 6.48 | 0.240 | 0.255 | |
| J(1) | 2.41 | 2.92 | 0.095 | 0.115 | |
| L | 13.35 | 14.02 | 0.526 | 0.552 | |
| L(1) | 3.32 | 3.82 | 0.131 | 0.150 | |
| ØР | 3.54 | 3.94 | 0.139 | 0.155 | |
| Q | 2.60 | 3.00 | 0.102 | 0.118 | |

DWG: 5471

Notes

* M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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